

**AMENDMENTS TO THE CLAIMS**

1. (Currently Amended) An imaging apparatus comprising:

an imaging portion in which a cover glass is adhered to an imaging surface side of a solid-state image pickup device as if sandwiching leads, a slight air gap is formed between the cover glass and the imaging surface of the solid-state image pickup device and a circumference of the cover glass is larger than the solid-state image pickup device, and

a circuit board having an accommodation concave portion for accommodating the solid-state image pickup device so as to connect the leads to terminals on an upper edge of the accommodation concave portion,

wherein the concave portion forms a clearance between a first adhesion area and a second adhesion area, the first adhesion area being between the solid state image sensor and the cover glass, and thea second adhesion area being between the cover glass and the circuit board, wherein the first adhesion area and the second adhesion area are on a same side of the cover glass;

wherein the adhesion area between the cover glass and the circuit board adheres to the circuit board in a state of sealing the accommodation concave portion.

2-5. (Canceled)